

The logo for Microbond, featuring a stylized blue wave above the word "MICROBOND" in a bold, sans-serif font.

## Microbond® SMT660 Innolot® No-Clean Printing T4 Solder Paste

Microbond® SMT660 Innolot® paste stands for highly reliable, high-performance paste with a competitive Total Cost of Ownership (TCO) offering. Innolot® is a well-known alloy, allowing for higher creep resistance, resulting in longer product life-cycles at higher operating temperatures. The SMT660 Innolot® solder paste performs in air without additional N<sub>2</sub> during reflow, while keeping defects low, reducing your TCO. This specifically means reduced pin and blowhole behavior, very low BGA voiding and low area voiding.

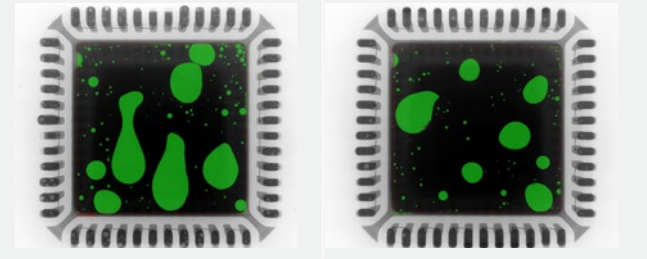
### Key Features

- Innolot® solder paste solderable in air with low defects
- Acrylic-based synthetic resin ensuring stable quality
- Reduced pin and blowhole behavior
- High reliability alloy and high SIR performance
- Low area voiding
- Halogen zero

### Voiding example on MLF 48 processed in air

Conventional Innolot® solder paste

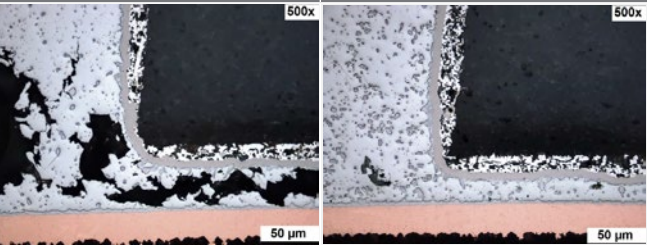
SMT660 Innolot®



### Cross section on a 1206 resistor after 2000 hours temperature cycling test from -40 °C to 125 °C

SAC305

Innolot®



### Product properties Microbond® SMT660 Innolot®

Alloy	Innolot®
Metal content	89%
Powder type	Type 4
Halogen content	Halogen zero
Flux classification	No-clean

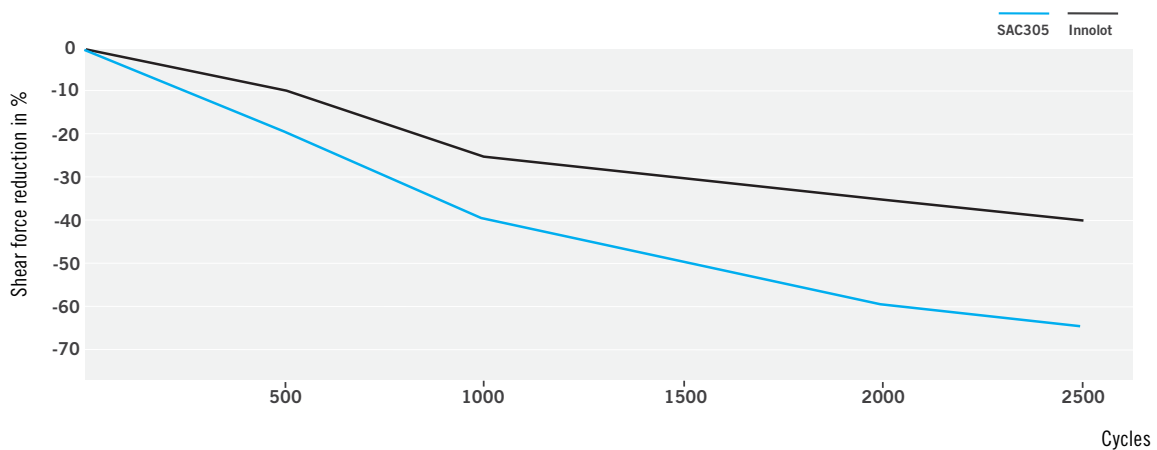
### Powder properties

Particle size	20 - 38 µm
Alloy	Sn/Ag3.8/Cu0.7/Ni0.15/Sb1.5/Bi3
Melting point	206 - 218 °C

### Storage

Temperature	2 - 10 °C
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### Reliability on chip resistor 1206 with chemical tin finish and temperature cycling from -40 °C to 125 °C



#### Americas

Phone +1 610 825 6050

electronics.americas@heraeus.com

#### Asia Pacific

Phone +65 6571 7649

electronics.apac@heraeus.com

#### China

Phone +86 53 5815 9601

electronics.china@heraeus.com

#### Europe, Middle East and Africa

Phone +49 6181 35 4370

electronics.emea@heraeus.com

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Heraeus Electronics GmbH & Co.KG, 63450 Hanau, Germany  
Web: www.heraeus-electronics.com

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